Overview

HP 250 15.6 inch G9 Notebook PC



Left

- 1. Internal Dual Digital Microphone
- 2. Webcam LED
- 3. Webcam
- 4. Touchpad
- 5. Touchpad Buttons
- 6. Audio Combo Jack
- 1. SuperSpeed USB 20Gbps is not available.

- 7. Power Indicator LED
- 8. Hard Drive Indicator LED
- **9.** SuperSpeed USB Type-C[®] 5Gbps signaling rate¹ (Data Transfer Only)
- 10. HDMI Port (Cable Sold Separately)
- 11. RJ-45 / Ethernet Port
- 12. Power Button

Overview



Right

- 1. Power Connector
- 2. SuperSpeed USB Type-A 5Gbps signaling rate¹ port 5. (USB 3.2 Gen 1)
- **3.** SuperSpeed USB Type-A 5Gbps signaling rate¹ port (USB 3.2 Gen 1)
- 1. SuperSpeed USB 20Gbps is not available.

- 4. SD Card slot
 - Fingerprint Reader (Selected models)

AT A GLANCE

Overview

- Preinstalled with Windows 11 Pro, Window Home or FreeDOS
- Choice of 12th generation Intel® Core™, Intel® Pentium®, or Intel® Celeron® processors
- Choice of 39.62 cm (15.6") diagonal HD and Ultra Wide Viewing Angle FHD 300 nit display
- NVIDIA® GeForce® MX550 (2 GB GDDR6 dedicated) (Optional)
- Optimize your video calls with an HD camera and temporal noise reduction that adjusts the lighting to your environment.
- Fast dual channel DDR4 SODIMM memory up to 32 GB
- Enhanced security features including discrete TPM 2.0 (select model) and optional Fingerprint reader
- Weight with basic configurations starting at 3.84 lb / 1.74 kg
- Support wireless options for connectivity on the go including gigabit-speed up to Wi-Fi 6
- Supports fast charging (50% in 45 minutes) with no impact on battery recharge cycles
- MM18 Battery life up to 8hours and 20 minutes
- Full size, optional backlit keyboard and clickpad with Precision Touchpad Supported certified
- Passed 13 MIL-STD test

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP 250 15.6 inch G9 Notebook PC

OPERATING SYSTEM

Preinstalled Windows 11 Pro ¹

Windows 11 Pro Education¹

Windows 11 Home - HP recommends Windows 11 Pro for business 1

Windows 11 Home Single Language - HP recommends Windows 11 Pro for business ^{1,2}

Windows 11 Home Education - HP recommends Windows 11 Pro for business ¹

FreeDOS

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- 2. This computer is preinstalled with Windows 11 Home Single Language.

PROCESSORS

Γ		,4,5,6,7 Cores Threads L5 1-core and		Max Fre	quency		
	Processor ^{3,4,5,6,7}			Threads Cache	1-core and 2-core	3-core and 4-core	Base Frequency
				Cacile	burst	burst	
	Intel® Pentium® Silver N600	4	4	4MB	3.3 GHz	3.1 GHz	1.1 GHz
	Intel® Celeron® N4500	2	2	4MB	2.8 GHz	NA	1.1 GHz

Processor	Carac	Number of	Number of	Threade	hreads Cacha 🗀	Max Turbo Frequency		Base Frequency	
3,4,5,6,7	Cores	P-cores	E-cores	inreaus		P-cores	E-cores	P-cores	E-cores
Intel® Core™ i7-1255U	10	2	8	12	12MB	4.7 GHz	3.5 GHz	1.7 GHz	1.2 GHz
Intel® Core TM i7-1260P	12	4	8	16	18MB	4.7 GHz	3.4 GHz	2.1 GHz	1.5 GHz
Intel® Core TM i5-1240P	12	4	8	16	12MB	4.4 GHz	3.3 GHz	1.2 GHz	1.3 GHz
Intel® Core TM i5-1235U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.3 GHz	0.9 GHz
Intel® Core TM i3-1215U	6	2	4	8	10MB	4.4 GHz	3.3 GHz	1.2 GHz	0.9 GHz

^{3.} Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Technical Specifications

- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.
- 7. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on produ configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated

Intel® UHD Graphics
Intel® Iris® X? Graphics 8

Discrete

NVIDIA® GeForce® MX550 (2 GB DDR6 dedicated) 9

Supports

Support HD decode, DX12, HDMI 1.4b 10

- 8. Intel® Iris® X? Graphics capabilities require system to be configured with Intel® CoreTM i5 or i7 processors and dual channel memory. Intel® Iris® X? Graphics with Intel® CoreTM i5 or 7 processors and single channel memory will only function as UHD graphics.
- 9. Integrated graphics depends on processor. NVIDIA® OptimusTM technology requires an Intel processor, plus an NVIDIA® GeForce discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA® OptimusTM technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).
- 10. HD content required to view HD images.

DISPLAY



Technical Specifications

Non-Touch

39.6 cm (15.6") diagonal, FHD (1920 x 1080), Low Blue Light, anti-glare, UWVA, micro-edge, 300 nits, sRGB 100% eDP 1.4+PSR2

39.6 cm (15.6") diagonal, FHD (1920 x 1080), anti-glare, SVA, micro-edge, 250 nits, 45% NTSC eDP 1.2 $^{10.11.12}$ 39.6 cm (15.6") diagonal, FHD (1920 x 1080), anti-glare, UWVA, micro-edge, 250 nits, 45% NTSC eDP 1.2 $^{10.11.12}$

39.6 cm (15.6") diagonal, HD (1366x768), anti-glare, SVA, micro-edge, 250 nits, 45% NTSC eDP 1.2 10.11.12

HDMI

Port supports resolutions up to 1920 x 1080 external resolution @60 Hz

Display Size

15.6" diagonal 39.6 cm (15.6") diagonal

- 10. HD content required to view HD images.
- 11. Sold separately or as an optional feature.
- 12. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Primary Storage

1 TB 5400 rpm SATA ¹³ 500 GB 7200 rpm SATA ¹³ 500 GB 5400 rpm SATA ¹³

Primary M.2 Storage

1 TB PCIe® NVMeTM M.2 Value Solid State Drive ¹³ 512 GB PCIe® NVMeTM M.2 TLC M.2 Solid State Drive ¹³ 512 GB PCIe® NVMeTM M.2 Value Solid State Drive ¹³ 256 GB PCIe® NVMeTM M.2 Value Solid State Drive ¹³ 128 GB PCIe® NVMeTM M.2 TLC M.2 Solid State Drive ¹³

Dual Storage (select models) 14

256 GB PCIe® NVMeTM M.2 Value Solid State Drive + 1TB 5400rpm SATA 128 GB M.2 SATA-3 TLC Solid State Drive + 1TB 5400rpm SATA

- 13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 11) is reserved for system recovery software.
- 14. JSL don't support dual storage due to design limitation.

Technical Specifications

MEMORY

Maximum Memory

32 GB DDR4-3200 SDRAM15,16

Memory

8 GB DDR4-2933 SDRAM (1 x 8 GB) ^{15,16}
4 GB DDR4-2933 SDRAM (2 x 16 GB) ^{15,16}
32 GB DDR4-3200 SDRAM (2 x 16 GB) ^{15,16}
16 GB DDR4-3200 SDRAM (1 x 16 GB) ^{15,16}
16 GB DDR4-3200 SDRAM (2 x 8 GB) ^{15,16}
12 GB DDR4-3200 SDRAM (1 x 8 + 1 x 4 GB) ^{15,16}
8 GB DDR4-3200 SDRAM (1 x 8 GB) ^{15,16}
8 GB DDR4-3200 SDRAM (2 x 4 GB) ^{15,16}
4 GB DDR4-3200 SDRAM (1 x 4 GB) ^{15,16}

Memory Slots

1 SODIMM ^{15,16}
Support Single Channel Memory
2 SODIMM (select models) ^{15,16}
Both slots are customer non-accessible / non-upgradeable
Supports Dual Channel Memory

15. All slots are non-accessible / non-upgradeable.

16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensur compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WI AN

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + Bluetooth® 5 ¹⁷
Realtek RTL8852BE 802.11ax 2x2 Wi-Fi + BT5.2 ¹⁸
Realtek RTL8821CE 802.11a/b/g/n/ac (1x1) Wi-Fi® with Bluetooth® 4.2 Combo ¹⁷

Miracast

Compatible with Miracast-certified devices (For Win11) 19

Ethernet

Realtek RTL8111HSH 10/100/1000 Integrated NIC. 20

- 17. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
- 18. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi Fi 6 is backwards compatible with prior 802.11 specs.
- 19. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
- 20. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Technical Specifications

AUDIO/MULTIMEDIA

Audio

2 Integrated stereo speakers Integrated dual array microphone

Speaker Power

2W/4ohm

Camera

720p HD camera with Temporal Noise Reduction 11

11. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Full Size Textured island-style Keyboard and optional Backlit 12

Pointing Device

Touchpad with multi-touch gesture support (PTP certified)

Function Keys

- F1 Open " How to get help in Windows 11" webpage
- F2 Brightness Down
- F3 Brightness Up
- F4 Display Switching
- F5 Blank
- F6 Mute
- F7 Volume Down
- F8 -Volume Up
- F9 Previous
- F10 Play/Pause
- F11 Next
- F12 Airplane mode
- 12. Sold separately or as an optional feature

SOFTWARE AND SECURITY

Technical Specifications

Software

MYOffice

MyHP

HP QuickDrop²¹

HP Privacy Settings

HP SUPPORT ASSISTANT 22

HP Audio Switch

HP Connection Optimizer

HP PC Hardware Diagnostics

HP Smart Health

HP Smart²³

Manageability Features

Touchpoint Customizer for Consumer

NOTE: To enhance brightness, level go to the Intel® Graphics Command Center app, click on System and turn off the Display Power Savings function.

Security Management

McAfee Security (30 days free trial as default) ²⁴ Express VPN (30 days free trial) LastPass password manager Discrete TPM 2.0 (select model) / Firmware TPM 2.0 ²⁵ Fingerprint Reader ²⁶

- 21. HP Quick Drop requires Internet access and Windows 10 and higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 22. HP Support Assistant requires Windows and Internet access.
- 23. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- 24. 30-day McAfee® LiveSafeTM trial included. Internet access required and not included. Subscription required after expiration. See www.McAfee.com for more details.
- 25. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 26. HP Fingerprint sensor is an optional feature that must be configured at purchase.

POWER

Technical Specifications

Power Supply

HP Smart 65 W External AC power adapter ²⁷ HP Smart 65 W EM External AC power adapter ²⁷ HP Smart 45 W External AC power adapter ²⁷

Battery

HP Long Life 3-cell, 41 Wh Li-ion Polymer ^{28,29} Compliant with UL 1642 Standard

Power Cord

1M (3.28 feet) length power cord

Battery Life

Up to 8 hours 20 minutes ³⁰ **Battery Weight**0.42 lb
0.19 kg

- 27. Availability may vary by country.
- 28. Battery is internal and not replaceable by customer. Serviceable by warranty.

29. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
30. Windows MM18 battery life will vary depending on various factors including product model, configuration, loaded applications features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight

Starting at 3.84 lb³¹ Starting at 1.74 kg³¹

Product Dimensions (W x D x H)

14.09 x 9.53 x 0.78 in 35.8 x 24.2 x 1.99 cm

31. Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

Technical Specifications

Ports

2 SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1)
1 SuperSpeed USB Type-C[®] 5Gbps signaling rate (Data Transfer Only)

1 HDMI v1.4b 32

1 RJ-45

1 AC Power

1 Headphone/microphone combo jack

Expansion Slots

support SD/SDHC/SDXC

1 multi-format digital media reader

32. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extende coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. ³³

33. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

SYSTEM UNIT

Stand-Alone Power Requirements

(AC Power)

Nominal Operating Voltage 19.5 V Average Operating Power 6.3W Integrated graphics Yes

Discrete Graphics N/A (Switchable graphics design)

Max Operating Power Discrete < 65W

UMA < 45W

Temperature

Operating 32° to 95° F (0° to 35° C) (not writing optical)

41° to 95° F (5° to 35° C) (writing optical)

Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity

Technical Specifications

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%

Shock

Operating 40 G, 2 ms duration, half-sine Non-operating 240 G, 2 ms duration, half-sine

Random Vibration

Operating 1.043 grams
Non-operating 3.5 grams

Altitude (unpressurized)

Operating -15 m to 3048 m (-50 ft to 10000 ft) Non-operating -15 m to 12192 m (-50 ft to 40000 ft)

Planned Industry Standard

Certifications

Regulatory Model Number TPN-C139
UL Yes
CSA No
FCC Compliance Yes
ENERGY STAR® Yes³⁴

EPEAT® Yes, EPEAT® registered 35

ICES Yes Australia / Yes NZ A-Tick Compliance Yes CCCYes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes CU/EAC Yes CIT N/A Saudi Arabian Compliance (ICCP) Yes **SABS** Yes **UKRSERTCOMPUTER** Yes

34. Configurations of the HP 250 G9 Notebook PC that are ENERGY STAR® qualified are identified as HP 250 G9 Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.

35. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or HP Sure View.

Technical Specifications

15.6 in FHD (1920 x 1080) Anti-Glare UWVA Low Blue Light sRGB NWBZ 300 eDP 1.4+PSR2 100 flat LCD Panel Outline Dimensions (W x H) 350.66*215.34(With PCBA) typ +/- 0.5

Active Area 344.16 x 193.59 typ

Weight 310g max Diagonal Size 15.6"

Thickness 2.45 typ /2.6 max

Interface eDP1.4
Surface Treatment Anti-Glare
Touch Enabled No
Contrast Ratio 1000:1 typ
Refresh Rate 60Hz
Brightness 300nits typ

Pixel Resolution 1920 x 1080 (FHD)

Format WLED Backlight RGB

Color Gamut Coverage sRGB100% typ

Color Depth 8bits

Viewing Angle UWVA 89/89/89

Low Blue Light Yes

Power Consumption (W, EBL@ 2.69W max / 3.34W max

150nits max/ 200nits max)

15.6-in FHD (1920x1080) Anti-Glare WLED SVA 45percent cg 250nits eDP 1.2 w/o PSR NWBZ ultraslim **Outline Dimensions (W x H)** 350.96 * 216.65 (max. w/ PCB)

Active Area 344.16 x 193.59 typ

Weight 360g max
Diagonal Size 15.6"
Thickness 3.2mm max
Interface eDP1.2
Surface Treatment Anti-Glare

Touch Enabled No
Contrast Ratio 300:1 typ
Refresh Rate 60Hz
Brightness 250nits typ
Pixel Resolution 1920 x 1080 (FHD)

Format WLED
Backlight RGB
Color Gamut Coverage NTSC45%
Color Depth 6bit

Viewing Angle SVA 45/45/15/35

Low Blue Light No

Power Consumption (W, EBL@ 2.67W max / 3.33W max

150nits max/ 200nits max)

Technical Specifications

15.6-in FHD (1920x1080) Anti-Glare WLED UWVA 45percent cg 250nits eDP 1.2 w/o PSR NWBZ slim

 Outline Dimensions (W x H)
 350.96*216.75(max.)

 Active Area
 344.16 x 193.59 (typ.)

370g max. Weight 15.6" **Diagonal Size** 3.2 max. **Thickness** eDP1.2 Interface Anti-Glare **Surface Treatment** No **Touch Enabled** 600:1 typ **Contrast Ratio** 60Hz **Refresh Rate**

Brightness 250nits typ **Pixel Resolution** 1920 x 1080 (FHD)

Format WLED

Backlight RGB

Color Gamut Coverage NTSC45%

Color Depth 6bits

Viewing Angle UWVA 85/85/85

Low Blue Light No
Power Consumption (W, EBL@ 2.75W max

150nits max/200nits max)

15.6-in HD (1366x768) Anti-Glare WLED SVA 45percent cg 250nits eDP 1.2 w/o PSR NWBZ ultraslim

Outline Dimensions (W x H) 350.96 * 216.65 (max. w/ PCB)

Active Area 344.23 x 193.54 typ

360g max Weight 15.6" Diagonal Size 3.2mm max **Thickness** eDP1.2 Interface Anti-Glare **Surface Treatment** No **Touch Enabled** 300:1 typ **Contrast Ratio** 60Hz **Refresh Rate** 250nits typ **Brightness** 1366 x 768 (HD) **Pixel Resolution**

Format WLED

Backlight RGB

Color Gamut Coverage NTSC45%

Color Depth 6bits

Viewing Angle SVA 45/45/15/35

Low Blue Light No

Power Consumption (W, EBL@ 2.42W max / 2.98W max

150nits max/ 200nits max)

STORAGE and drives

Technical Specifications

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 11) is reserved for system recovery software.

HDD 1TB 5400RPM 7mm SATA

Drive Weight 0.21 lbs (95 a) **Rotation speed** 5400rpm **NAND Type** up to 128MB Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Weight ATA-8, SATA 3.0 Interface 600MB/s (Interface) **Maximum Sequential Read** Single Track: 1.5ms Agerage: 13ms

Maximum: 32ms

Maximum Sequential Write

1.953.525.168

Logical Blocks

0° to 60°C [case temp]

Operating Temperature

ATA Security

Features

S.M.A.R.T., NCO, Ultra DMA

HDD 500GB 5400RPM 7mm **SATA**

Drive Weight 0.21 lbs (95 g) Rotation speed 5400rpm **Cache Buffer** up to 128MB **NAND Type/Size** N/A

Height 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 **Transfer Rate** 600MB/s (Interface) **Seek Time** Single Track: 1.5ms

Agerage: 13ms Maximum: 32ms

Logical Blocks 976.773.168

Operating Temperature 0° to 60°C [case temp] **Security Features**

ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

Technical Specifications

HDD 500GB 7200RPM 7mm SATA

Drive Weight 0.21 lbs (95 a) **Rotation speed** 7200rpm **Cache Buffer** up to 128MB Heiaht 0.28 in (7 mm) Width 2.75 in (69.85 mm) Interface ATA-8, SATA 3.0 **Transfer Rate** 600MB/s (Interface) **Seek Time** Single Track: 1.5ms Agerage: 13ms

Maximum: 32ms

Logical Blocks 976,773,168

Operating Temperature 0° to 60°C [case temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

64GB eMMC 5.x

Form Factor eMMC Capacity 64GB **NAND Type** MLC/TLC Height 1.4mm Width 11.5x13mm Weight 0.2a

Interface MMC protocal **Maximum Sequential Read** Update to 250MB/s **Maximum Sequential Write** Update to 70MB/s

Logical Blocks 64GB(62.537.072.640 Bytes)

Operating Temperature 0 to 70 **Features HS400**

SSD 128GB 2280 PCIe-3x2 **Three Layer Cell**

Form Factor M.2 2280 Capacity 128GB NAND Type TLC

Height 0.09 in (2.3 mm) Width 0.87 in (2.2 mm) Interface PCIe NVMe Gen3X4 **Maximum Sequential Read** up to 1600MB/s ±20% **Maximum Sequential Write** up to 900MB/s ±20%

Logical Blocks 250.069.680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pvrite

Technical Specifications

SSD 1TB 2280 PCIe NVMe Value

Form Factor M.2 2280
Capacity 1TB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe NVMe

Maximum Sequential Readup to 2300MB/s $\pm 20\%$ Maximum Sequential Writeup to 2000MB/s $\pm 20\%$ Logical Blocks2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite

SSD 256GB 2280 PCIe NVMe Value

Form Factor M.2 2280
Capacity 256GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (2.2 mm)

 Weight
 0.02 lb (10 a)

 Interface
 PCIe NVMe

Logical Blocks 500.118.192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pvrite

SSD 512GB 2280 PCIe NVMe Value

Me Form Factor M.2 2280
Capacity 512GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (2.2 mm)

 Interface
 PCIe NVMe

Maximum Sequential Readup to 2300MB/s $\pm 20\%$ Maximum Sequential Writeup to 1400MB/s $\pm 20\%$ Logical Blocks1.000.215.216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pvrite

Technical Specifications

SSD 512GB 2280 M2 PCIe-3x4 SS NVMe TLC Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (2.2 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read up to 3100MB/s ±20%
Maximum Sequential Write up to 2400MB/s ±20%

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite

SSD 512GB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (2.2 mm)

Weight

Interface PCIe NVMe Gen4X4

Maximum Sequential Read up to 6000MB/s ±20%

Maximum Sequential Write up to 4000MB/s ±20%

Locior Blocks

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite

NETWORKING/Communications

Realtek 802.11a/b/g/n/ac Wireless LAN Standards IEEE 802.11a (1x1) Wi-Fi® and IEEE 802.11b Bluetooth® 4.2 Combo ¹ IEEE 802.11g

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11d
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11r
IEEE 802.11v

InteroperabilityWi-Fi certified modulesFrequency Band● 802.11b/g/n

2.402 - 2.482 GHz

802.11a/n/ac

4.9 - 4.95 GHz (Japan)

Technical Specifications

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

● 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

802.11n: max 150Mbps802.11ac: max 433.3Mbps

Modulation Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³ IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification WPA3 certification IEEE 802.11i WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² 802.11b: +14dBm minimum

802.11g : +12dBm minimum 802.11a : +12dBm minimum

802.11n HT20(2.4GHz): +12dBm minimum 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum 802.11n HT40(5GHz): +10dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna.

One embedded dual band 2.4/5 GHz antenna is provided to the card to

support WLAN communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard



Technical Specifications

Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230 : 2.8g

 Operating Voltage
 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)"

Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF;

LED OFF - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2 Compliant **Frequency Band** 2402 to 2480 MHz

Number of AvailableLegacy : 0~79 (1 MHz/CH)ChannelsBLE : 0~39 (2 MHz/CH)

Data Rates andLegacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput**BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.

- 1. Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8852BE Wireless LAN Standards IEEE 802.11a
802.11ax 2x2 Wi-Fi® + IEEE 802.11b
Bluetooth® 5.2 (802.11ax
2x2, supporting gigabit data rate) 1 IEEE 802.11ac
IEEE 802.11ac
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11d
IEEE 802.11e

IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Technical Specifications

Interoperability Wi-Fi certified modules **Frequency Band** 802.11b/g/n/ax 2.402 - 2.482 GHz 802.11a/n/ac/ax 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz **Data Rates** • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac: max 866.7Mbps 802.11ax: max 1201Mbps **Direct Sequence Spread Spectrum** Modulation BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM Security³ IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification • IEEE 802.11i WAPI **Network Architecture** Ad-hoc (Peer to Peer) Models Infrastructure (Access Point Required) Roaming IEEE 802.11 compliant roaming between access points Output Power² 802.11b: +18.5dBm minimum 802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum 802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ax HE40(2.4GHz): +10dBm minimum • 802.11ax HE80(5GHz): +10dBm minimum Transmit mode: 2.5 W **Power Consumption** Receive mode: 2 W Idle mode (PSP)180 mW(WLAN Associated)

Idle mode:50 mW(WLAN unassociated)

Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Technical Specifications

Receiver Sensitivity⁴ • 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum

802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum

802.11ac, MCS0 : -84dBm maximum802.11ac, MCS9 : -59dBm maximum

802.11ax, MCS11(HE40): -57dBm maximum
802.11ax, MCS11(HE80): -54dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF

LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1/5.2 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH)
Channels BLE: 0~39 (2 MHz/CH)

Data Rates andLegacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput**BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.

1.Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

Technical Specifications

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + Bluetooth® 5

Wireless LAN Standards IEEE 802.11a

> IEEE 802.11b IEEE 802.11q IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v

Interoperability

Wi-Fi certified modules

Frequency Band

802.11b/g/n

2.402 - 2.482 GHz

802.11a/n/ac

4.9 - 4.95 GHz (Japan)

5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

 802.11n: max 300Mbps 802.11ac : max 866.7Mbps

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security3

IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification WPA3 certification IEEE 802.11i

WAPI

Network Architecture

Ad-hoc (Peer to Peer)

Models

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power2 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum 802.11n HT40(2.4GHz): +14.5dBm minimum 802.11n HT20(5GHz): +15.5dBm minimum 802.11n HT40(5GHz): +14.5dBm minimum

Technical Specifications

802.11ac VHT80(5GHz): +11.5dBm minimum

Power Consumption Transmit mode :2.0 W

Receive mode: 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode :50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity4 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

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2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230 : 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber - Radio OFF

LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy : 0~79 (1 MHz/CH)
Channels BLE : 0~39 (2 MHz/CH)

Data Rates andLegacy: 3 Mbps data rate; throughput up to 2.17 Mbps **Throughput**BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with a

maximum transmit power of + 4 dBm for BR and EDR.



Technical Specifications

- 1. Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTK8111HSH 10/100/1000 Integrated NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
	Manageability	Wake-on-LAN from modern standby or sleep state (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) (MSC is supported on selected model) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status

POWER

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

Technical Specifications

HP 65W Smart AC adapter

Dimensions (H x W x D) 90x51x28.5mm

Weight 230g +/- 10g (Not including power cord. Power cord varies by country.)

Input 100 to 240 VAC

> Input Efficiency 88.0 % at 115 VAC and 89.0 % at 230VAC

48 ~ 63 Hz Input frequency range

Input AC current Max. 1.7 A at 90 VAC

Output **Output power** 65W DC output

19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A Over voltage protection- 29V max

automatic shutdown

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords **Environmental Design**

Operating temperature 32°F to 95°F (0° to 35°C) -4°F to 185°F (-20° to 85°C) Non-operating (storage)

temperature

Altitude 1 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Eq:

*CE Mark - full compliance with LVD and EMC directives Certifications

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1

and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV;

Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

45 W AC adapter

Dimensions 95x40x26.5mm

Weight 200g +/- 10g (Not including power cord. Power cord varies by country.)

Input 100 to 240 VAC

> **Input Efficiency** 88.0 % at 115 VAC and 89.0 % at 230VAC

48 ~ 63 Hz Input frequency range

Max. 1.4 A at 90 VA **Input AC current**

45W Output **Output power**

19.5V DC output

5ms at 115 Vac input Hold-up time

<8.0A Over voltage protection- 29V max

Output current limit automatic shutdown

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

32°F to 95°F (0°to 35°C) **Environmental Design** Operating temperature

-4°F to 185°F (-20°to 85°C) Non-operating (storage)

temperature

Altitude 1 to 16,400 ft (0 to 5,000m)

Humidity 20% to 95% 10% to 95% **Storage Humidity**

EMI and Safety

*CE Mark - full compliance with LVD and EMC directives **Certifications**



Technical Specifications

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV;

Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W EM Smart AC adapter

Dimensions 102x55x30mm

Weight 250g +/- 10g (Not including power cord. Power cord varies by country.)

Input 100 to 240 VAC

Input Efficiency 88.0 % at 115 VAC and 89.0 % at 230VAC

Input frequency 48 ~ 63 Hz

range

Input AC current Max. 1.7 A at 90 VAC

Output Output power 65W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <11.0A Over voltage protection- 29V max

automatic shutdown

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating 32°Fto 95°F (0°to 35°C)

temperature

Non-operating -4°Fto 185°F (-20°to 85°C)

(storage) temperature

Altitude 1 to 16,400 ft (0 to 5,000m)

Humidity 20% to 95 **Storage Humidity** 10% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1

and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV;

Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.

Technical Specifications

HP 3-cell Long Life Li-Ion (41 Wh¹) **Dimensions (H x W x L)** 6.0 x 186.85 x 90.2 mm (0.23 x 7.29 x 3.52 inch)

Weight 0.175 Kg (0.385 lb)

Cells/Type 3cell lithium-Ion Polymer cell 515974

Energy

Voltage 11.34V/11.28V **Amp-hour capacity** 3.62Ah/3.635Ah

Watt-hour capacity 41Wh

Temperature

Operating (Charging) 32cto 113° F (0° to 45° C) **Operating (Discharging)** 14° to 122° F (-10° to 60° C)

Fuel Gauge LED N/A
Warranty 1-year
Optional Travel Battery No

Available

AUDIO

HD Stereo Codec Realtek ALC3247

Audio I/O Ports One Headset Combo-Jack connector support CTIA spec.

Internal Speaker Amplifier 2W class D stereo amplifier for the internal speaker only. External speakers must

be powered.

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow

independent audio streams to be sent to/from the Combo jack or integrated

speaker.

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to

24-bit: 44.1 kHz to 48 kHz for DAC and ADC.

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes.
of Channels on Line-Out 0
Internal Speaker Yes

FINGERPRINT READER

Sensor vendor Elan eFSA80ST touch sensor

Sensor type Capacitive
DPI resolution 508 DPI
Scan area 200 HO Sensor type

80 x 80 pixels array

False Rejection Rate FRR (False Reject Rate) / FAR (False Acceptance Rate):

FRR ~ 2% @ 1:50K FAR

False Acceptance Rate

Mobile Voltage Operation 2.65V to 3.6V

Operating Temperature 32° to 95° F (0° to 35° C)

Current Consumption Image50mA peakLow Latency Wait For Finger<900 uA</th>Capture Rate20cm/sec

ESD Resistance IEC 61000-4-2 (+15KV)

Detection Matrix 508 dpi / 4x4mm sensor area

Technical Specifications

ENVIRONMENTAL DATA

ENVIRONIVIEN I AL L & Eco-Label Certifications	-	r is in the process of heing ce	ertified to the following approvals and may be				
declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:						
dectar actoris	IT ECO declaration						
		 US ENERGY STAR® US Federal Energy Management Program (FEMP) 					
			EAT ® registration varies by				
			stration status by country.*				
			ding to IEEE 1680.1-2018				
			ttp://www.epeat.net for more				
	information.	varies by country. Visit if	itp://www.cpcat.net for more				
	TCO Certified						
		vation Program (CECP)					
		nental Protection Administra	tion (SEPA)				
	Taiwan Green Mark	Terretar Forcetton Marininger	1011 (321 71)				
	Korea Eco-label						
	Japan PC Green label*						
Sustainable Impact	• 5% post-consume						
Specifications	Low halogen						
•		corrugated cushions are	100% sustainably sourced and				
	recyclable	3	,				
	-	p Cushion inside box is	100% sustainably sourced and				
	recyclable	p Guerrieri inerae bek ie	10070 Gudiamasiy Godi God and				
	Bulk packaging available						
System Configuration	Declared Noise Emissions data for the ebook"?.						
Energy Consumption							
(in accordance with US							
ENERGY STAR® test							
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz				
Normal Operation (Sort							
idle)	4.97 W	4.94 W	4.87 W				
Normal Operation (Long							
idle)	2.74 W	2.79 W	2.72 W				
Sleep	0.42 W	0.42 W	0.44 W				
Off	0.14 W	0.14 W	0.17 W				
		J 1 11	•				
	Note:						
	Energy efficiency data liste	d is for an ENERGY STAR® cor	npliant product if offered within the model				
	Energy efficiency data lister family. HP computers mark	d is for an ENERGY STAR® cor ed with the ENERGY STAR® Lo	npliant product if offered within the model ogo are compliant with the applicable U.S.				
	Energy efficiency data lister family. HP computers mark Environmental Protection A	d is for an ENERGY STAR® cor ed with the ENERGY STAR® Lo Igency (EPA) ENERGY STAR® !	npliant product if offered within the model ogo are compliant with the applicable U.S. specifications for computers. If a model fami				
	Energy efficiency data lister family. HP computers mark Environmental Protection A does not offer ENERGY STAI	d is for an ENERGY STAR® cor ed with the ENERGY STAR® Lo Igency (EPA) ENERGY STAR® ! R® compliant configurations,	npliant product if offered within the model ogo are compliant with the applicable U.S. specifications for computers. If a model famil then energy efficiency data listed is for a				
	Energy efficiency data lister family. HP computers mark Environmental Protection A does not offer ENERGY STAI typically configured PC feat	d is for an ENERGY STAR® cor ed with the ENERGY STAR® Lo Agency (EPA) ENERGY STAR® s R® compliant configurations, curing a hard disk drive, a high	npliant product if offered within the model ogo are compliant with the applicable U.S. specifications for computers. If a model famil				
	Energy efficiency data lister family. HP computers mark Environmental Protection A does not offer ENERGY STAI	d is for an ENERGY STAR® cor ed with the ENERGY STAR® Lo Agency (EPA) ENERGY STAR® s R® compliant configurations, curing a hard disk drive, a high	npliant product if offered within the model ogo are compliant with the applicable U.S. specifications for computers. If a model famil then energy efficiency data listed is for a				
Heat Dissipation*	Energy efficiency data lister family. HP computers mark Environmental Protection A does not offer ENERGY STAI typically configured PC feat	d is for an ENERGY STAR® cor ed with the ENERGY STAR® Lo Agency (EPA) ENERGY STAR® s R® compliant configurations, curing a hard disk drive, a high	npliant product if offered within the model ogo are compliant with the applicable U.S. specifications for computers. If a model famil then energy efficiency data listed is for a				

Technical Specifications

Normal Operation (Short					
idle)	17 BTU/hr	16.9 BTU/hr	16.7 BTU/hr		
Normal Operation (Long	_				
idle)	9.4 BTU/hr	9.5 BTU/hr	9.3 BTU/hr		
Sleep	1.4 BTU/hr	1.4 BTU/hr	1.5 BTU/hr		
Off	0.5 BTU/hr	0.5 BTU/hr	0.6 BTU/hr		
	*NOTE: Heat dissipation is c attained for one hour.	alculated based on the mea	asured watts, assuming the service level is		
Declared Noise Emissions	Sound Powe	r	Sound Pressure		
(in accordance with	(L _{WAd} , bels)	'	(L _{DAm} , decibels)		
ISO 7779 and ISO 9296)	(LWAG, Dets)		(LpAm, decibets)		
-	0.7		40.0		
Typically Configured - Idle	2.7		16.2		
Fixed Disk - Random writes	2.8		18.6		
Optical Drive - Sequential reads	N/A		N/A		
Longevity and Upgrading	This product can be upgra	aded nossibly extending i	ts useful life by several years.		
gerity and opgraumy	Upgradeable features and				
Additional Information	directive - 2011/65/E This HP product is a Equipment (WEEE) This product is in concentration of the Drinking Water and This product is in consee www.epeat.net Plastics parts weigh and ISO1043. This product is 94.2	s HP product is designed to comply with the Waste Electrical and Electronic lipment (WEEE) Directive - 2002/96/EC. s product is in compliance with California Proposition 65 (State of California; Safe aking Water and Toxic Enforcement Act of 1986). s product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level www.epeat.net stics parts weighing over 25 grams used in the product are marked per ISO11469			
Packaging Materials	External: PAPER/	Corrugated	295 g		
	PAPER/	Molded Pulp	141 g		
	Internal: PLASTIC	C/Polyethylene low densi	y - LDPE 10 g		
	PLASTIC	C/Polypropylene - PP	4 g		
	The plastic packaging ma		~		
			is at least 57.0% recycled content.		
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances-including PVC, BFRs, and certain phthalates-in future RoHS legislation that pertains to electrical and electronics products.				

Technical Specifications

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

Technical Specifications

	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals
	excluded.
	 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	Fiber cushions made from 100% recycled wood fiber and organic materials.

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part Number
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
	HP 500 BT Headset	53L34AA
	HP 365 BT Speaker	567D3AA
Cases	HP Prelude Backpack 15.6	1E7D6AA
	HP Prelude Top Load 15.6	1E7D7AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Renew Business 17.3" Backpack	3E2U5AA
	HP Renew Business 15.6" Bag	3E5F8AA
	HP Renew Business 17.3" Bag	3E2U6AA
Hub	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP USB 3.0 to Gigabit Adapter	N7P47AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gig RJ45 Adapter G2	4Z7Z7AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1DOK8AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
	HP 235 Slim Wireless Mouse	4E407AA
Power	HP 65W Smart AC Adapter	Н6Ү89АА
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA

Summary of Changes

Date of change	Version History		Description of change
March 14, 2022	V1 to V2	Added	Battery Compliance in Power section; Environmental Data section
April 11, 2022	V2 to V3	Added	Reference for USB ports
April 25, 2022	V3 to V4	Added	MIL-STD test in At a Glance section
June 10, 2022	V4 to V5	Updated	TechSpecs
June 15 , 2022	V5 to V6	Added	Added note in Manageability Feature

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